

MEASURING METHOD

ABSTRACT

A measuring method includes storing thickness data of each of chips held on a holding surface of a holding table, the thickness data being obtained by measurement of thicknesses of portions of the chip at a plurality of measurement points and representing the thicknesses measured at the measurement points in association with positions of the measurement points in a predetermined plane corresponding to a reverse side of the wafer, storing positions of central lines of dividing grooves in the predetermined plane in captured images of reverse sides of the chips, setting, in a periphery of each of the chips, a thickness data unreferencing zone including measurement points where the thickness data will not be referenced in calculating the thickness of the chip, and calculating, for each of the chips, an average value of thicknesses at the measurement points except for the measurement points included in the thickness data unreferencing zone.

[FIG. 4]